SCLS020E - MARCH 1984 - REVISED AUGUST 2003

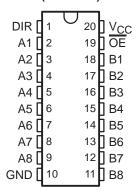
- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current 3-State Outputs Drive Bus Lines Directly or Up To 15 LSTTL Loads
- Low Power Consumption, 80-μA Max I_{CC}
- Typical t_{pd} = 14 ns
- ±6-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible

description/ordering information

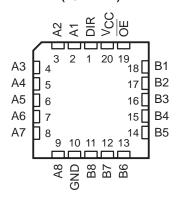
These octal bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation minimizes external timing requirements.

The 'HCT245 devices allow data transmission from the A bus to the B bus or from the B bus to the A bus, depending upon the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so that the buses are effectively isolated.

SN54HCT245 ... J OR W PACKAGE SN74HCT245 ... DB, DW, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HCT245 . . . FK PACKAGE (TOP VIEW)



ORDERING INFORMATION

TA	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74HCT245N	SN74HCT245N
	SOIC - DW	Tube of 25	SN74HCT245DW	HCT245
	30IC - DVV	Reel of 2000	SN74HCT245DWR	HC1245
-40°C to 85°C	SOP - NS	Reel of 2000	SN74HCT245NSR	HCT245
-40 C to 65 C	SSOP - DB	Reel of 2000	SN74HCT245DBR	HT245
		Tube of 70	SN74HCT245PW	
	TSSOP - PW	Reel of 2000	SN74HCT245PWR	HT245
		Reel of 250	SN74HCT245PWT	
	CDIP – J	Tube of 20	SNJ54HCT245J	SNJ54HCT245J
–55°C to 125°C	CFP – W	Tube of 85	SNJ54HCT245W	SNJ54HCT245W
	LCCC – FK	Tube of 55	SNJ54HCT245FK	SNJ54HCT245FK

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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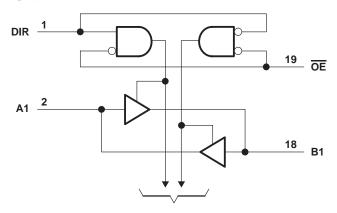


processing does not necessarily include testing of all parameters.

FUNCTION TABLE

INP	UTS	OPERATION				
OE	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	Χ	Isolation				

logic diagram (positive logic)



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		0.5 V to 7 V
Input clamp current, IIK (VI < 0 or VI > VCC) (se	e Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)	±20 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	• • • • • • • • • • • • • • • • • • • •	±35 mA
Continuous current through V _{CC} or GND		±70 mA
Package thermal impedance, θ_{JA} (see Note 2):	DB package	70°C/W
	DW package	58°C/W
	N package	69°C/W
	NS package	60°C/W
	PW package	83°C/W
Storage temperature range, T _{sto}		. −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 3)

			SN	54HCT2	45	SN	74HCT2	45	UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	2			2			V
VIL	Low-level input voltage	V _{CC} = 4.5 V to 5.5 V			0.8			0.8	V
٧ _I	Input voltage		0		VCC	0		VCC	V
Vo	Output voltage		0		VCC	0		VCC	V
Δt/Δν	Input transition rise/fall time				500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		Voc	Т	A = 25°C	;	SN54H	CT245	SN74H	CT245	UNIT
FAR	AWETER	1231 00	NDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	ONIT
Va		\\ \\ or \\	$I_{OH} = -20 \mu A$	4.5 V	4.4	4.499		4.4		4.4		V
VOH		$V_I = V_{IH} \text{ or } V_{IL}$	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		V
Vai		\\ \\ or \\	, I _{OL} = 20 μA			0.001	0.1		0.1		0.1	V
VOL		VI = VIH or VIL IOL = 6 mA		4.5 V		0.17	0.26		0.4		0.33	V
П	DIR or OE	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100		±1000		±1000	nA
loz	A or B	VO = VCC or 0		5.5 V		±0.01	±0.5		±10		±5	μΑ
Icc		$V_I = V_{CC}$ or 0,	I _O = 0	5.5 V			8		160		80	μΑ
∆lcc†		One input at 0.5 \ Other inputs at 0		5.5 V		1.4	2.4		3		2.9	mA
C _i ‡	DIR or OE			4.5 V to 5.5 V		3	10		10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

PARAMETER	ARAMETER FROM TO		Vaa	T,	չ = 25°C	;	SN54H	CT245	SN74H	CT245	UNIT		
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT		
	A or B	B or A	4.5 V		16	22		33		28	ns		
^t pd	AOIB	BOIA	5.5 V		14	20		30		25	110		
+	ŌĒ	A or B	4.5 V		25	46		69		58	ns		
t _{en}	OE		5.5 V		22	41		62		52	115		
.	<u></u>	A or B	4.5 V		26	40		60		50	ns		
^t dis	OE	OE A or B	5.5 V		23	36		54		45	110		
4.		A or P	4.5 V		9	12		18		15	no		
t _t			A or E	AUIB	5.5 V		8	11		16		14	ns

[‡] Parameter C_i does not apply to transceiver I/O ports.

SN54HCT245, SN74HCT245 OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended operating free-air temperature range, C_L = 150 pF (unless otherwise noted) (see Figure 1)

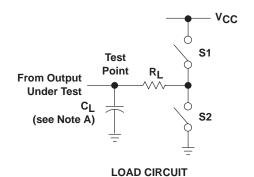
PARAMETER	FROM	FROM TO		T,	λ = 25°C	;	SN54H	CT245	SN74H	CT245	UNIT	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT	
+ .	A or B	B or A	4.5 V		20	30		45		38	nc	
^t pd	AOIB	BULA	5.5 V		18	27		41		34	ns	
	ŌĒ	A or B	4.5 V		36	59		89		74	no	
t _{en}	OE		5.5 V		30	53		80		67	ns	
t _t		A - 11 P	A or D	4.5 V		17	42		63		53	
		A or B	5.5 V		14	38		57		48	ns	

operating characteristics, $T_A = 25^{\circ}C$

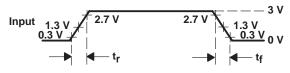
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd}	Power dissipation capacitance per transceiver	No load	40	pF



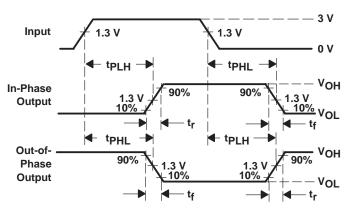
PARAMETER MEASUREMENT INFORMATION

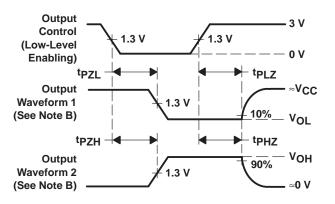


PARAN	PARAMETER		CL	S1	S2
	tPZH	1 k Ω	50 pF or	Open	Closed
ten '	tPZL	150 pF		Closed	Open
4	tPHZ	1 k Ω	50 pF	Open	Closed
^t dis	tPLZ	1 K22	30 pr	Closed	Open
t _{pd} or	t _{pd} or t _t — 50 pF or 150 pF		Open	Open	



VOLTAGE WAVEFORM INPUT RISE AND FALL TIMES





VOLTAGE WAVEFORMS
PROPAGATION DELAY AND OUTPUT RISE AND FALL TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C_L includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



14 LEADS SHOWN

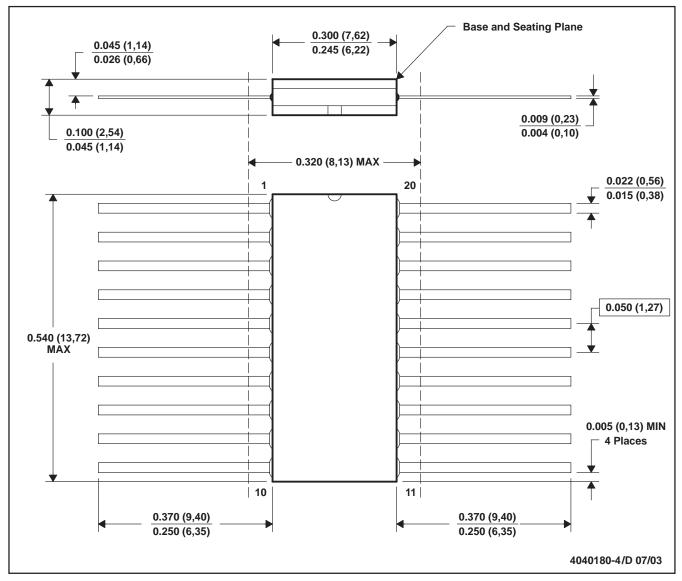


NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



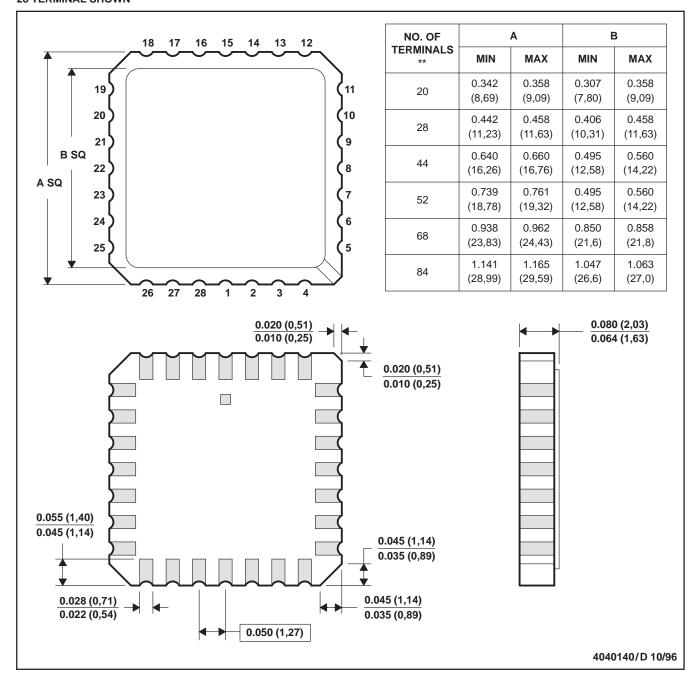
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20

FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



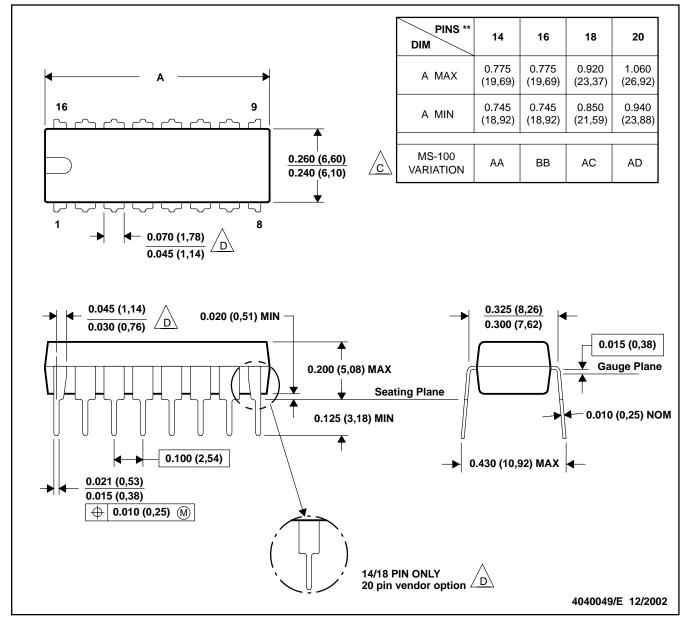
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

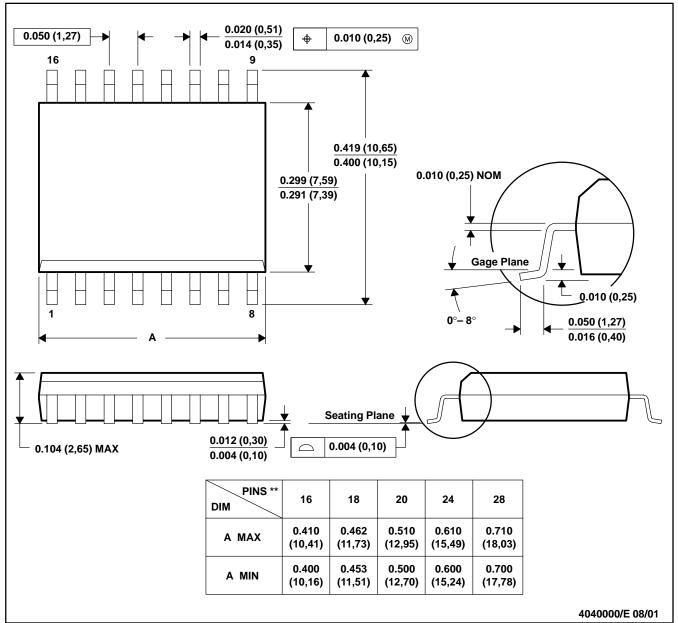
Falls within JEDEC MS-001, except 18 and 20 pin minimum body Irngth (Dim A).

The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

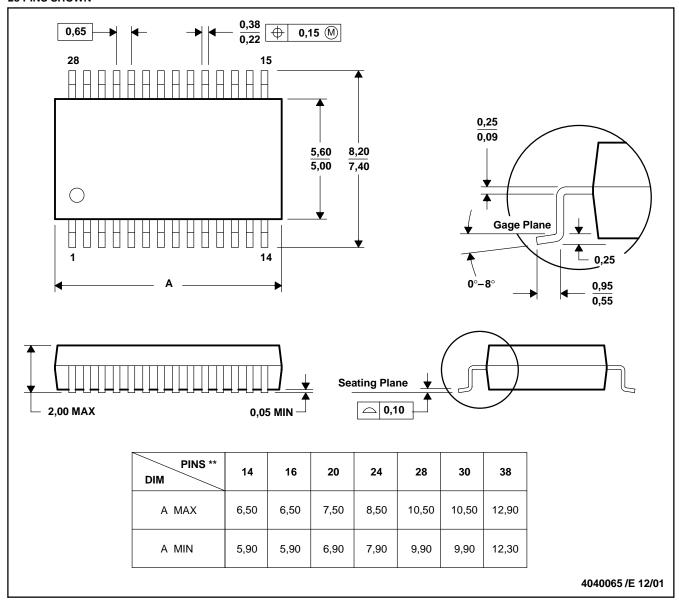
- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

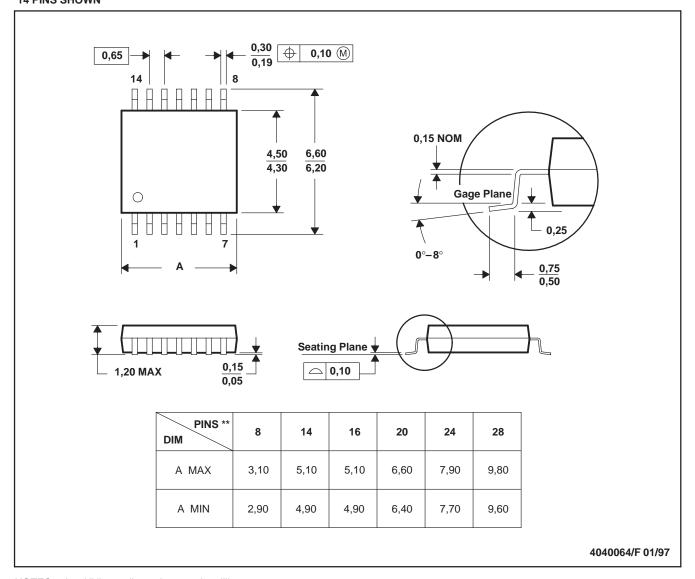
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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